Engineering Development Model

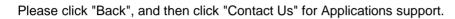
Low Pass Filter

SXLP-EDU1701

Surface Mount

Important Note

This model has been designed, built and tested in our engineering department. Performance data represents model capability. At present it is a non-catalog model. On request, we can supply a final specification sheet, part number and price/delivery information.



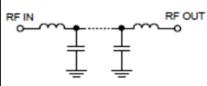


CASE STYLE: HF1139

ELECTRIC	AL SPECIFICAT	IONS 50Ω @ -	+25°C	
Parameter	Min.	Тур.	Max.	Units
Passband (Loss < 2 dB)	DC		2.5	MHz
Insertion loss 3 dB		2.9		MHz
Stopband (Loss > 20 dB)		4.2	200	MHz
(Loss > 40 dB)		5.5	200	MHz
Passband VSWR		1.5		(:1)
Stopband VSWR		20		(:1)

Functional Schematic

MAXIMUM RATINGS					
Operating Temperature	-40°C to 85°C				
Storage Temperature	-55°C to 100°C				
RF Power Input	200mW				



PIN CONNECTIONS						
Input 1						
Output	8					
Ground 2,3,4,5,6,7						

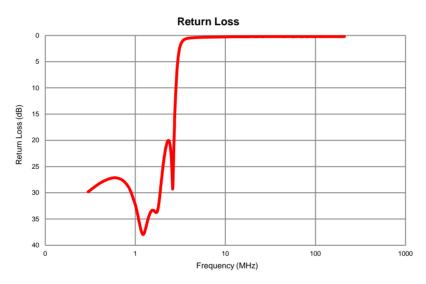
Typical Performance Data

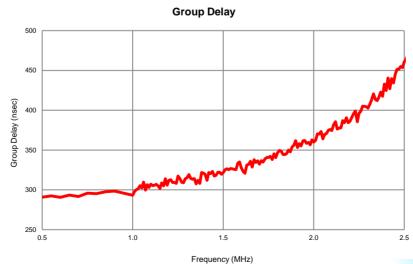
FREQUENCY	INSERTION LOSS	RETURN LOSS	FREQUENC	GROUP DELAY
(MHz)	(dB)	(dB)	(MHz)	(nsec)
0.3	0.10	29.81	0.3	289.15
0.5	0.11	27.39	0.4	290.19
1.0	0.16	32.26	0.5	290.88
1.5	0.25	33.50	0.6	290.54
1.8	0.33	32.76	0.7	291.72
2.0	0.41	25.89	0.8	295.24
2.5	0.72	22.93	0.9	298.46
2.9	2.78	6.70	1.0	293.24
3.5	17.11	0.78	1.1	307.21
4.2	31.82	0.47	1.2	312.04
5.0	44.60	0.39	1.3	315.09
5.5	51.23	0.36	1.4	319.53
8.0	79.11	0.30	1.5	321.70
10.0	91.45	0.28	1.6	327.55
30.0	91.82	0.23	1.7	332.25
50.0	88.88	0.23	1.8	346.63
60.0	93.93	0.23	1.9	361.75
80.0	97.76	0.24	2.0	359.97
100.0	93.28	0.23	2.1	374.46
120.0	93.82	0.23	2.2	385.92
150.0	95.01	0.23	2.3	402.58
170.0	88.19	0.22	2.4	424.83
190.0	85.60	0.22	2.5	460.82
200.0	98.75	0.22	2.6	507.45



Typical Performance Curves









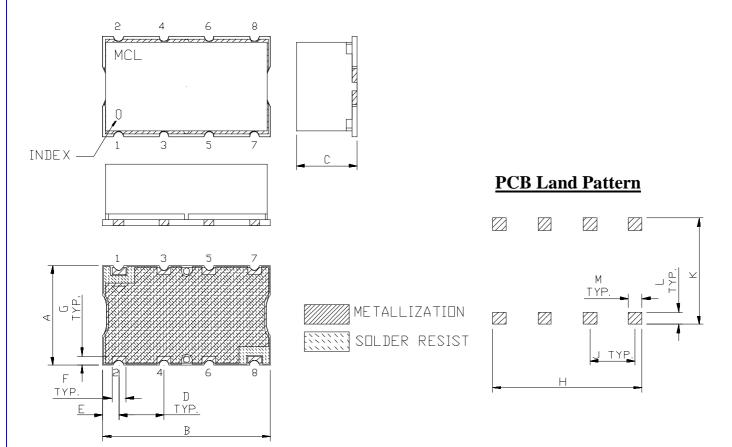


Case Style



HF1139

Outline Dimensions



CASE #	A	В	С	D	Е	F	G	Н	J	K	L	M	WT. GRAMS
HF1139	.44 (11.18)	.74 (18.80)	.27 (6.86)	.200 (5.08)	.07 (1.78)	.060 (1.52)	.040 (1.02)	.660 (16.76)	.200 (5.08)	.470 (11.94)	.055 (1.40)	.060 (1.52)	3.0

Dimensions are in inches (mm). Tolerances: 2 Pl. ±.015"; 3 Pl. ±.01"

Notes:

1. Case material: Nickel-Silver alloy.

2. Base: Printed wiring laminate.

3. Termination finish:

For RoHS Case Styles: $2-5 \mu$ inch (.05-.13 microns) Gold over 120-240 μ inch (3.05-6.10 microns) Nickel plate.

For RoHS-5 Case Styles: Tin-Lead plate.





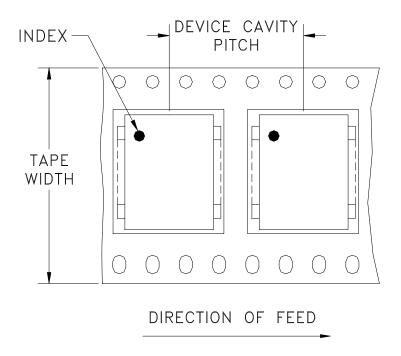
P.O. Box 350166, Brooklyn, New York 11235-0003 (718) 934-4500 Fax (718) 332-4661 For detailed performance specs & shopping online see Mini-Circuits web site

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RF/IF MICROWAVE COMPONENTS

Tape & Reel Packaging TR-F5

DEVICE ORIENTATION IN T&R



Tape Width,	Device Cavity	Reel Size,	Devices per Reel
mm	Pitch, mm	inches	
32	16	13	500

Mini-Circuits carrier tape materials provide protection from ESD (Electro-Static Discharge) during handling and transportation. Tapes are static dissipative and comply with industry standards EIA-481/EIA-541.

Go to: www.minicircuits.com/pages/pdfs/tape.pdf

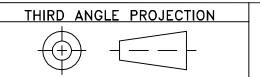


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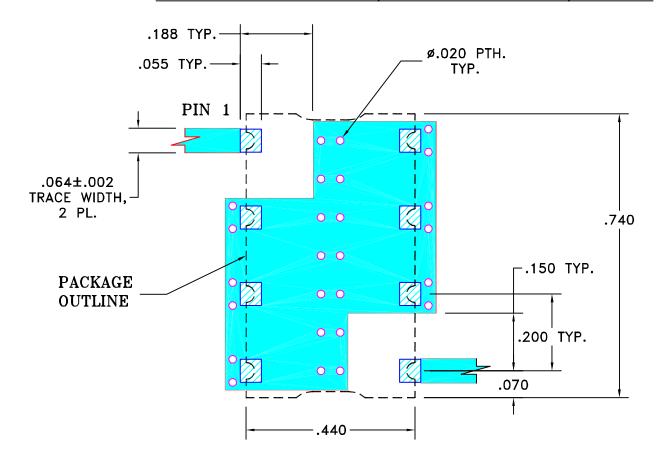
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	REVISIONS								
REV	ECN No.	DESCRIPTION	DATE	DR	AUTH				
OR	M101757	NEW RELEASE (FROM RAVON)	11/05	DK	HH				
OR	R62293	NEW RELEASE (FROM RAVON)	11/05	DK	HH				

SUGGESTED MOUNTING CONFIGURATION FOR HF1139 CASE STYLE, er PIN CONNECTION, 50 OHM.



NOTE:

- 1. TRACE WIDTH IS SHOWN FOR FR4 WITH DIELECTRIC THICKNESS: .025"±.002". COPPER: 1/2 OZ. EACH SIDE. FOR OTHER MATERIALS TRACE WIDTH MAY NEED TO BE MODIFIED.
- 2. BOTTOM SIDE OF THE PCB IS CONTINUOUS GROUND PLANE.

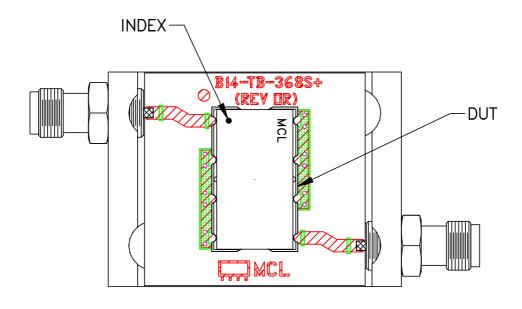


DENOTES PCB COPPER LAYOUT WITH SMOBC (SOLDER MASK OVER BARE COPPER)

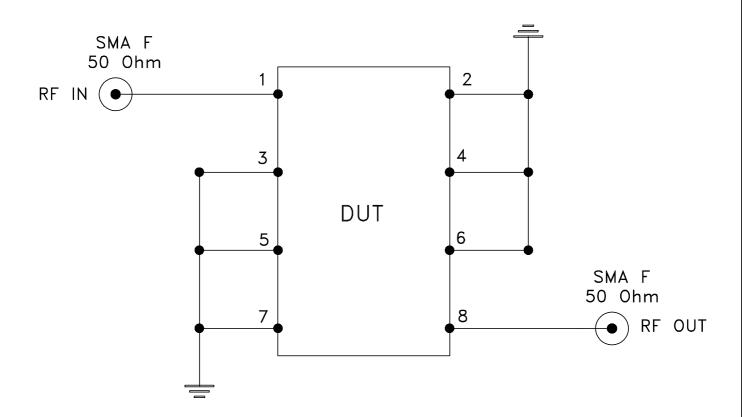
DENOTES COPPER LAND PATTERN FREE OF SOLDER MASK

UNLESS OTHERWISE SPECIFIED		INITIALS	DATE			. ~		(R)			
DIMENSIONS ARE IN INCHES	DRAWN	DK (RAVON)	29 NOV 05		Mini	ı — C	ircu	its	13 Neptus	ne Aveni	ue
TOLERANCES ON: 2 PL DECIMALS ±	CHECKED	RZ (RAVON)	29 NOV 05		Γ				Brooklyn	NI 1123	20
3 PL DECIMALS ± .005	APPROVED	HH (RAVON)	29 NOV 05] n	L, cr,	UT:11	20 5	ा छ	тъ	260	
FRACTIONS ±				P	L, Cr,	пгіі	139, 3	CLF,	ID-	300	
∏ Mini−	Mini-Circuits ®										
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Evaluation Board and Circuit



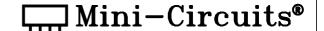
TB-368



Schematic Diagram

Notes:

- SMA Female connectors.
 PCB Material: ROGERS R04350B or equivalent, Dielectric Constant=3.5, Thickness=.030 inch.





Environmental Specifications

ENV02T1

All Mini-Circuits products are manufactured under exacting quality assurance and control standards, and are capable of meeting published specifications after being subjected to any or all of the following physical and environmental test.

Specification	Test/Inspection Condition	Reference/Spec
Operating Temperature	-40° to 85°C Ambient Environment	Individual Model Data Sheet
Storage Temperature	-55° to 100° C Ambient Environment	Individual Model Data Sheet
Humidity	90 to 95% RH, 240 hours, 50°C	MIL-STD-202, Method 103, Condition A, Except 50°C and end-point electrical test done within 12 hours
Thermal Shock	-55° to 100°C, 100 cycles	MIL-STD-202, Method 107, Condition A-3, except +100°C
Solder Reflow Heat	Sn-Pb Eutetic Process: 225°C peak Pb-Free Process 245° - 250°C peak	J-STD-020, Table 4-1, 4-2 and 5-2, Figure 5-1
Solderability	10X Magnification	J-STD-002, 95% Coverage
Vibration (High Frequency)	20g peak, 10-2000 Hz, 12 times in each of three perpendicular directions (total 36)	MIL-STD-202, Method 204, Condition D
Mechanical Shock	50g, 11 ms, 1/2-sine, 18 shocks: 3 each direction, each of 3 axes	MIL-STD-202, Method 213, Condition A
Marking Resistance to Solvents	Isopropyl alcohol + mineral spirits at 25°C; terpene defluxer at 25°C; distilled water + proylene glycol monomethyl ether + monoethanolamine at 63°C to 70°C	MIL-STD-202, Method 215

ENV02T1 Rev: B

02/25/11

M130240 File: ENV02T1.pdf

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